



Device Selection Guide

Model Number	Chip		Description
	Material	Emitting Color	
PDM58230x-G05	InGaN	True Green	Common Cathode x=C / Common Anode x=A
PDM58230x-G17	AlInGaP	Yellow Green	
PDM58230x-Y04		Yellow	
PDM58230x-A11		Amber	
PDM58230x-R02		Orange-Red	
PDM58230x-R11		Red	
PDM58230x-R21		Deep Red	

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating		Unit
		G17/Y04/A11/R02/R11/R21	G05	
Power Dissipation per Dice	PAD	70	114	mW
Derating Liner from 25°C per Dice	--	0.33	0.4	mA/°C
Continuous Forward Current Per Dice	IAF	25	30	mA
Peak Current Per Dice (duty cycle 1/10, 1KHz)	IPF	90	100	mA
Reverse Voltage Per Dice	VR	5	5	V
Electrostatic Discharge (HBM)	ESD	/	1000	V
Operating Temperature	Topr	-35~+85		°C
Storage Temperature	Tstg	-35~+85		°C

Solder Conditions: 1/16 inch below seating plane for 3 -5 seconds at 260°C.

Electrical and Optical Characteristics at Ta=25°C

Parameter	Symbol	Chip	Min.	Typ.	Max.	Unit	Condition
Forward Voltage Per Segment	VF	G05	--	3.2	3.8	V	IF=20mA
		G17/Y04/A11/R02/R11/R21	--	2	2.8		
Luminous Intensity Per Segment	Iv	G05	--	357	--	mcd	IF=10mA
		G17	--	22	--		
		Y04	--	69	--		
		A11	--	91	--		
		R02	--	55	--		
		R11	--	52	--		
		R21	--	27	--		
Peak Emission Wavelength / Dominant Wavelength	$\lambda P/\lambda d$	G05	--	*525	--	nm	IF=20mA
		G17	--	572/570	--		
		Y04	--	592/590	--		
		A11	--	612/605	--		
		R02	--	632/625	--		
		R11	--	644/630	--		
		R21	--	660/645	--		
Reverse Current	IR		--	--	100	μA	VR=5V
Luminous Intensity Matching Ratio	Iv-m		--	--	2:1	--	IF=10mA

Typical Electrical/Optical Characteristic Curves

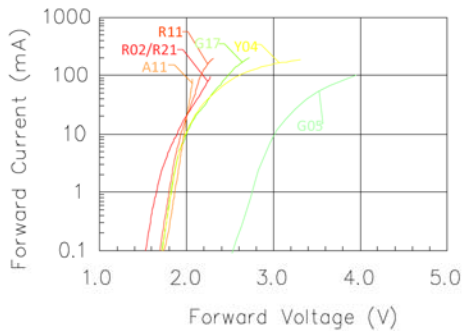


Fig 1. Forward Current vs. Forward Voltage

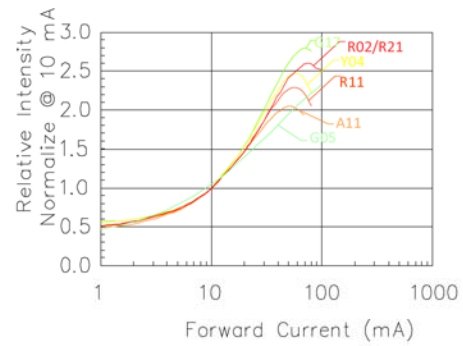


Fig 2. Relative Intensity vs. Forward Current

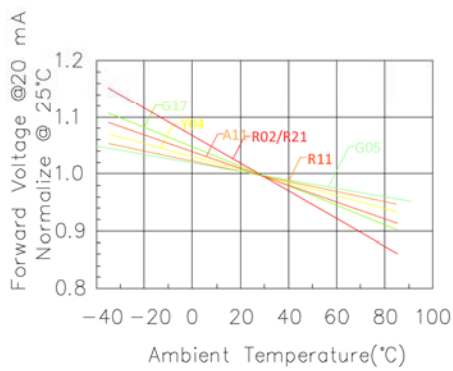


Fig 3. Forward Voltage vs. Temperature

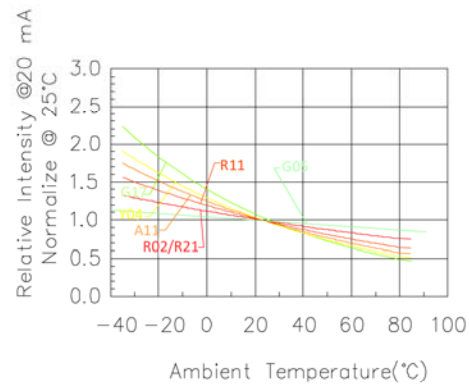


Fig 4. Relative Intensity vs. Temperature

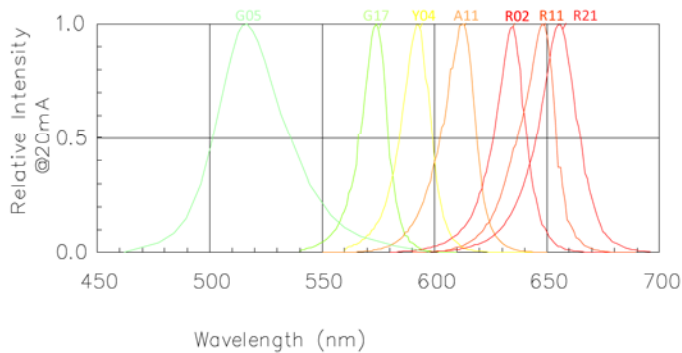


Fig 5. Relative Intensity vs. Wavelength

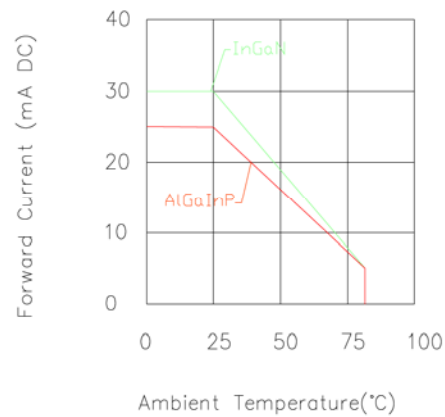


Fig 3. Forward Current vs. Ambient Temperature

Luminous General lv Bin Grade (IF = 10mA)
Color Rank Limits (IF=20mA)

Remark: Unit=mcd

*Tolerance: ±20%

●Pure Green(G05)

1	2	3	4	5
263.185	342.142	444.786	578.222	751.690
342.141	444.785	578.221	751.689	977.197

Remark: Unit=nm

*Tolerance: ±1

1	2	3	4	5
515.0	518.0	520.0	522.0	524.0
518.0	520.0	522.0	524.0	527.0

●Yellow Green(G17)

N	P	Q	R	S
14.682	19.088	24.815	32.261	41.940
19.087	24.814	32.260	41.939	54.522

0	1	2	3	4
567.5	569.5	570.5	571.5	573.0
569.4	570.4	571.4	572.9	575.0

●Yellow (Y04)

S	T	U	V	W
41.940	54.523	70.881	92.146	119.791
54.522	70.880	92.145	119.790	155.729

1	2	3	4	5
583.0	585.0	587.0	589.0	591.0
585.0	587.0	589.0	591.0	593.0

●Amber (A11)

T	U	V	W	X
54.523	70.881	92.146	119.791	155.730
70.880	92.145	119.790	155.729	202.449

●Orange (R02)

R	S	T	U	V
32.261	41.940	54.523	70.881	92.146
41.939	54.522	70.880	92.145	119.790

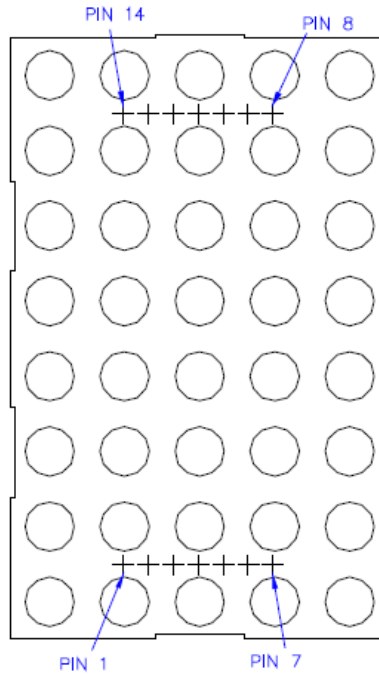
●Red (R11)

R	S	T	U	V
32.261	41.940	54.523	70.881	92.146
41.939	54.522	70.880	92.145	119.790

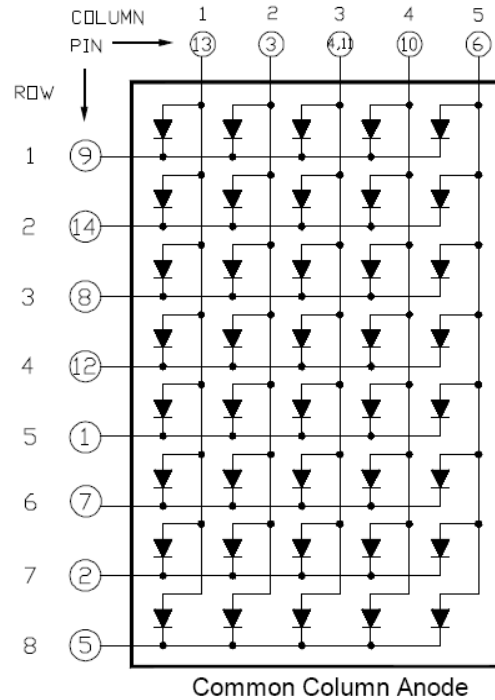
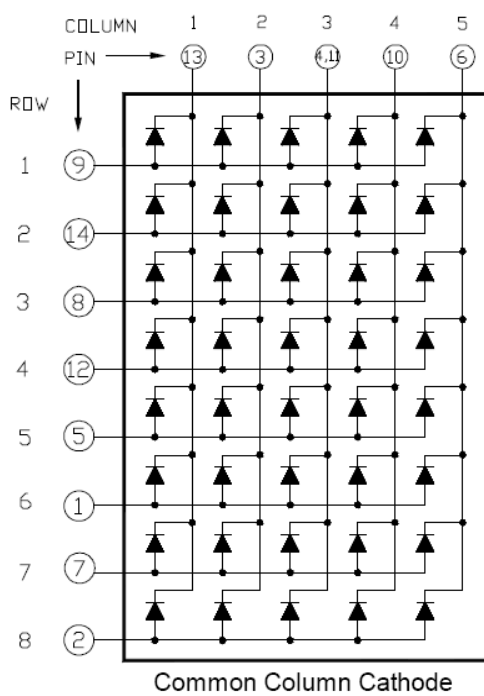
●Deep Red(R21)

N	P	Q	R	S
14.682	19.088	24.815	32.261	41.940
19.087	24.814	32.260	41.939	54.522

All Light-On Segments Feature & Pad Position



Internal Circuit Diagram

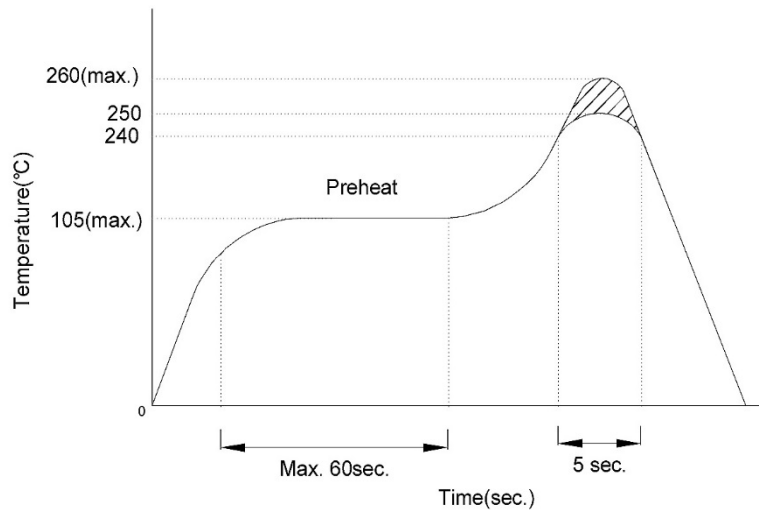


Precautions for Use

1. Recommended soldering conditions

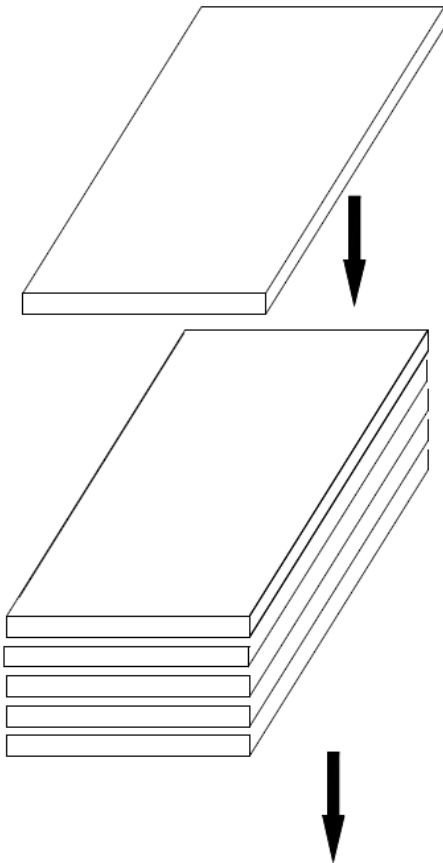
1.1. Wave soldering

Basic SPEC is $\leq 5\text{sec.}$ When 260°C. If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec.}$).

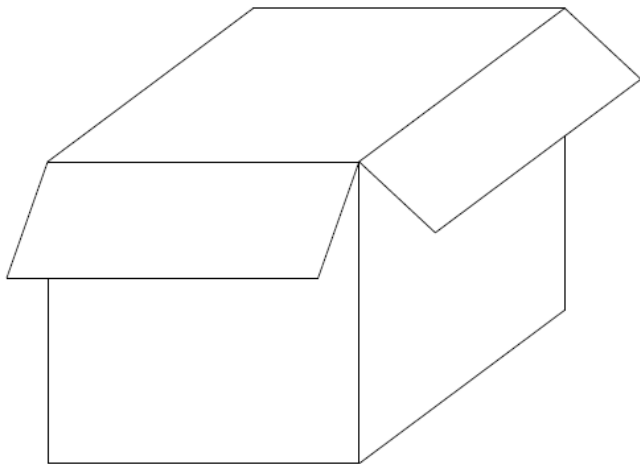


1.2. Soldering Iron:

Power dissipation of iron should be smaller than 15W and temp should be controllable. Soldering temperature should be under 260°C , time $\leq 3\text{sec.}$

Packing Dimensions

16 Pcs Per PE.foam
PE.foam Size:
L295xW195xH15mm



9 PE.foam Per Box
Q'TY: 144 PCS
Box Size:
L300*W205*H240mm